REMARKS/ARGUMENTS

Examiner's ruling with respect to the restriction of claims has been duly noted, Claims 7-24 and 30-39 have, accordingly, been canceled. One or more divisional applications will be filed at a later date to cover the canceled claims.

Reconsideration is requested of all rejections based on objections to the drawings:

All claims that previously referred to a 'heat source' now refer to a 'coil'. The latter appears in each of FIGs. 3-7 as element 17.

Reconsideration is requested of all rejections based on objections to the abstract:

A new abstract that conforms to the guidelines provided by examiner has been provided.

Reconsideration is requested of all rejections based on objections to the specification:

With the removal from the claims of all references to a 'heat source', antecedent basis for this term is no longer required.

Reconsideration is requested of all rejections based on objections to the claims:

With the removal from the claims of all references to a 'source', amendment of "source" to –heat source—is no longer required (or possible).

Reconsideration is requested of all rejections based on 35 U.S.C. 112:

The description of a layer of thermally conductive material that "contacts the pedestal and extends therefrom as far as the coil" has been replaced by --layer of thermally conductive material that connects the pedestal to the coil--. Examiner is thanked for pointing out the need for this improved wording.

As required by examiner, the qualifier "about" has been removed from all claims.

In response to examiner's comment, that the term "mutual alloys" does not make it clear which alloys are encompassed and which are excluded, we have amended the wording to --all alloys limited to these elements--. Should this still not satisfy examiner, a suggestion as to what would be acceptable wording, would be much appreciated.

Reconsideration is requested of all rejections based on 35 U.S.C. 102:

Examiner has relied for this rejection on Nakatani et al. which teaches a process to manufacture a printed circuit board that is thermally conductive and that has wiring on both sides. As examiner knows, a rejection based on 35 U.S.C. 102 is required to teach all features of the rejected claim. The following features of our claims 1 and 25 (as currently amended) are not taught by Nakatani:

(1) A method/structure to dissipate heat generated within a micro-structure.

(2) Dissipation of heat generated by a coil.

(3) A coil located within a micro-structure.

(4) Forming/providing a thermally conductive pedestal that extends upwards from the substrate. Examiner has argued that said pedestal is taught by Nakatani, stating that Nakatani discloses "conductive pedestal or sheet 700 extending away from ..... substrate 702...". We respectfully point out that element 700 is the substrate while element 702 is printed circuit wiring. Neither element is a pedestal.

(5) Forming/providing a layer of thermally conductive material that connects the pedestal to the coil.

Reconsideration is requested of all rejections based on 35 U.S.C. 103:

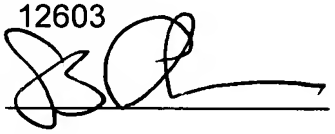
Claims 2, 4-6, 26, 28 and 29 are believed to be patentable and non-obvious over Nakatani for the reasons noted above in our response to the 102 rejection - that several elements, such as the claimed coil, of the instant claims are not disclosed by Nakatani, and therefore these claims are both novel and non-obvious with respect to Nakatani.

We note that claim 6 has been amended to conform to the proposed new wording of claim 1.

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Respectfully submitted,

Saile Ackerman LLC
28 Davis Avenue
Poughkeepsie
NY 12603

By 

Stephen B. Ackerman
Reg. No. 37761